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TinyLogic ULP-A 2-Input Non-Inverting Multiplexer

NC7SP157

The NC7SP157 is a 2-input non-inverting multiplexer in tiny footprint packages. The device is designed to operate for V_{CC} = 0.9 V to 3.6 V.

Features

- Designed for 0.9 V to 3.6 V V_{CC} Operation
- 2.9 ns t_{PD} at 3.3 V (Typ)
- Inputs/Outputs Over-Voltage Tolerant up to 3.6 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 2.6 mA at 3.3 V
- Available in SC-88 and MicroPakTM Packages
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

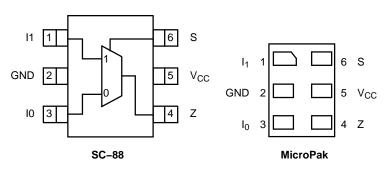


Figure 1. Pinout Diagrams (Top Views)

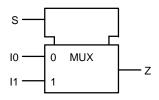


Figure 2. Logic Symbol

PIN ASSIGNMENT

Pin	SC88	MicroPak
1	I1	l1
2	GND	GND
3	10	10
4	Z	Z
5	V _{CC}	V _{CC}
6	S	S



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MARKING DIAGRAMS



SIP6 1.45X1.0 MicroPak CASE 127EB



CC = Specific Device Code

KK = 2-Digit Lot Run Traceability Code

XY = 2-Digit Date CodeZ = Assembly Plant Code



SC-88 DF SUFFIX CASE 419B-02



XXX = Specific Device Code

1 = Date Code

= Pb-Free Package

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 6 of this data sheet.

FUNCTION TABLE

	Inputs	Output	
S I1 I0		$Z = 10 \times \overline{S} + 11 \times S$	
L	Х	L	L
L	Х	Н	Н
Н	L	Х	L
Н	Н	Х	Н

MAXIMUM RATINGS

Symbol	Ch	aracteristics	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +4.3	V
V _{IN}	DC Input Voltage		-0.5 to +4.3	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +4.3 -0.5 to +4.3	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA
I _{OUT}	DC Output Source/Sink Current		±50	mA
I _{CC} or I _{GND}	DC Supply Current per Supply Pin	or Ground Pin	±50	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Cas	e for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 2)	SC–88 MicroPak	377 154	°C/W
P _D	Power Dissipation in Still Air	SC–88 MicroPak	332 812	mW
MSL	Moisture Sensitivity		Level 1	-
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V _{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
I _{Latchup}	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Applicable to devices with outputs that may be tri-stated.
 Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow per JESD51-7.
 HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.
- 4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parai	Min	Max	Unit	
V _{CC}	Positive DC Supply Voltage		0.9	3.6	V
V_{IN}	DC Input Voltage		0	3.6	V
V _{OUT}	DC Output Voltage	Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 3.6 3.6	
T _A	Operating Temperature Range		-40	+85	°C
t _r , t _f	Input Transition Rise and Fall Time	V_{CC} = 3.3 V \pm 0.3 V	0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

				Т	A = 25°	С	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
V_{IH}	High-Level Input		0.9	_	0.5	_	-	-	V
	Voltage		1.1 to 1.3	0.65 x V _{CC}	-	_	0.65 x V _{CC}	-	
			1.4 to 1.6	0.65 x V _{CC}	_	_	0.65 x V _{CC}	-	
			1.65 to 1.95	0.65 x V _{CC}	-	-	0.65 x V _{CC}	-	
			2.3 to 2.7	1.6	_	-	1.6	-	
			3.0 to 3.6	2.1	_	_	2.1	-	
V _{IL}	Low-Level Input		0.9	-	0.5	_	-	-	V
	Voltage		1.1 to 1.3	-	_	0.35 x V _{CC}	-	0.35 x V _{CC}	
			1.4 to 1.6	-	_	0.35 x V _{CC}	-	0.35 x V _{CC}	
			1.65 to 1.95	_	_	0.35 x V _{CC}	-	0.35 x V _{CC}	
			2.3 to 2.7	-	_	0.7	-	0.7	
			3.0 to 3.6	_	_	0.9	_	0.9	
V _{OH}	High-Level Output	$V_{IN} = V_{IH}$ or V_{IL}							V
	Voltage	I _{OH} = -20 μA	0.9	-	V _{CC} - 0.1	-	-	-	
			1.1 to 1.3	V _{CC} - 0.1	_	_	V _{CC} – 0.1	-	
			1.4 to 1.6	V _{CC} - 0.1	_	_	V _{CC} - 0.1	-	
			1.65 to 1.95	V _{CC} - 0.1	_	_	V _{CC} - 0.1	-	
			2.3 to 2.7	V _{CC} - 0.1	_	_	V _{CC} - 0.1	-	
			3.0 to 3.6	V _{CC} - 0.1	_	_	V _{CC} – 0.1	-	
		$I_{OH} = -0.5 \text{ mA}$	1.1 to 1.3	0.75 x V _{CC}	_	_	0.70 x V _{CC}	-	
		$I_{OH} = -1 \text{ mA}$	1.4 to 1.6	1.07	-	-	0.99	-	
		$I_{OH} = -1.5 \text{ mA}$	1.65 to 1.95	1.24	-	_	1.22	-	
		$I_{OH} = -2.1 \text{ mA}$	2.3 to 2.7	1.95	-	-	1.87	-	
		$I_{OH} = -2.6 \text{ mA}$	3.0 to 3.6	2.61	_	-	2.55	-	
V_{OL}	Low-Level Output	$V_{IN} = V_{IH}$ or V_{IL}							V
	Voltage	I _{OL} = 20 μA	0.9	_	0.1	_	-	-	
			1.1 to 1.3	_	-	0.1	-	0.1	
			1.4 to 1.6	_	-	0.1	-	0.1	
			1.65 to 1.95	-	-	0.1	-	0.1	
			2.3 to 2.7	_	-	0.1	-	0.1	
			3.0 to 3.6	_	_	0.1	-	0.1	
		$I_{OL} = 0.5 \text{ mA}$	1.1 to 1.3	-	_	0.3 x V _{CC}	-	0.3 x V _{CC}	
		I _{OL} = 1 mA	1.4 to 1.6	-	_	0.31	-	0.37	
		I _{OL} = 1.5 mA	1.65 to 1.95	_	_	0.31	-	0.35	
		I _{OL} = 2.1 mA	2.3 to 2.7	_	-	0.31	_	0.33	
		I _{OL} = 2.6 mA	3.0 to 3.6	_	-	0.31	-	0.33	
I _{IN}	Input Leakage Current	V _{IN} = 0 V to 3.6 V	0.9 to 3.6	-	_	±0.1	-	±0.5	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 0 V to 3.6 V or V _{OUT} = 0 V to 3.6 V	0	-	_	0.5	-	0.5	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	0.9 to 3.6	-	_	0.9	-	0.9	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

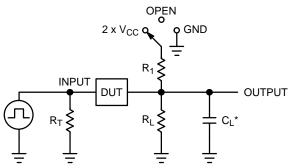
AC ELECTRICAL CHARACTERISTICS

				T _A = 25°C			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay,	$R_L = 1 \text{ M}\Omega$, $C_L = 10 \text{ pF}$	0.9	-	54.5	_	-	-	ns
	(S or I0 or I1) to Z (Figures 3 and 4)		1.10 to 1.30	-	14.6	32.3	-	37.7	
	,		1.40 to 1.60	-	7.6	15.1	_	16.8	
			1.65 to 1.95	-	5.4	11.5	_	12.5	
			2.3 to 2.7	-	3.6	8.1	-	9.1	
			3.0 to 3.6	-	2.9	6.6	_	7.7	
t _{PLH} , t _{PHL}	Propagation Delay,	r IO or I1) to Z	0.9	-	55.9	-	_	_	ns
	(S or I0 or I1) to Z (Figures 3 and 4)		1.10 to 1.30	-	15.1	33.7	-	39.7	
	,		1.40 to 1.60	-	8.0	16.0	_	17.2	
			1.65 to 1.95	-	5.8	12.1	-	13.1	
			2.3 to 2.7	-	3.8	8.6	_	9.7	
			3.0 to 3.6	-	3.1	7.0	-	8.1	
t _{PLH} , t _{PHL}	Propagation Delay,	$R_L = 1 \text{ M}\Omega$, $C_L = 30 \text{ pF}$	0.9	-	60.2	-	-	-	ns
	(S or I0 or I1) to Z (Figures 3 and 4)		1.10 to 1.30	-	16.7	37.8	_	47.7	
	,		1.40 to 1.60	-	9.3	18.6	-	19.5	1
			1.65 to 1.95	-	6.9	14.1	-	15.3	
			2.3 to 2.7	-	4.5	10.0	_	11.2	7
			3.0 to 3.6	-	3.7	8.2	-	9.3	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Test Condition	Typical (T _A = 25°C)	Unit
C _{IN}	Input Capacitance	V _{CC} = 0 V	2.0	pF
C _{OUT}	Output Capacitance	V _{CC} = 0 V	4.0	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	$f = 10 \text{ MHz}, V_{CC} = 0.9 \text{ to } 3.6 \text{ V}, V_{IN} = 0 \text{ V or } V_{CC}$	8.0	pF

^{5.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.



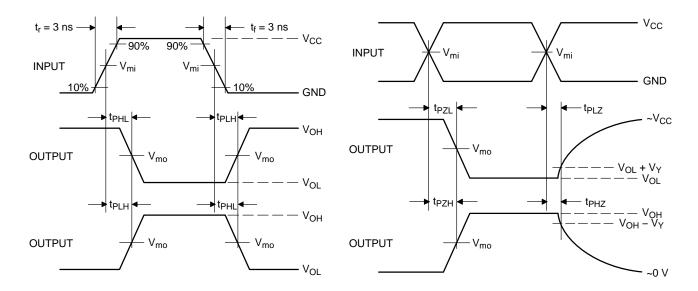
Test	Switch Position
t _{PLH} / t _{PHL}	Open
t _{PLZ} / t _{PZL}	2 x V _{CC}
t _{PHZ} / t _{PZH}	GND

 C_L includes probe and jig capacitance

 R_{T} is Z_{OUT} of pulse generator (typically 50 $\Omega)$

f = 1 MHz

Figure 3. Test Circuit



V _{CC} , V	V _{mi} , V	V_{mo} , V	V _Y , V
0.9	V _{CC} /2	V _{CC} / 2	0.1
1.1 to 1.3	V _{CC} /2	V _{CC} / 2	0.1
1.4 to 1.6	V _{CC} /2	V _{CC} /2	0.1
1.65 to 1.95	V _{CC} /2	V _{CC} /2	0.15
2.3 to 2.7	V _{CC} /2	V _{CC} /2	0.15
3.0 to 3.6	1.5	1.5	0.3

Figure 4. Switching Waveforms

ORDERING INFORMATION

Device	Package	Marking	Pin 1 Orientation (See below)	Shipping [†]
NC7SP157P6X	SC-88	PF7	Q4	3000 / Tape & Reel
NC7SP157L6X	MicroPak	L7	Q4	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Pin 1 Orientation in Tape and Reel

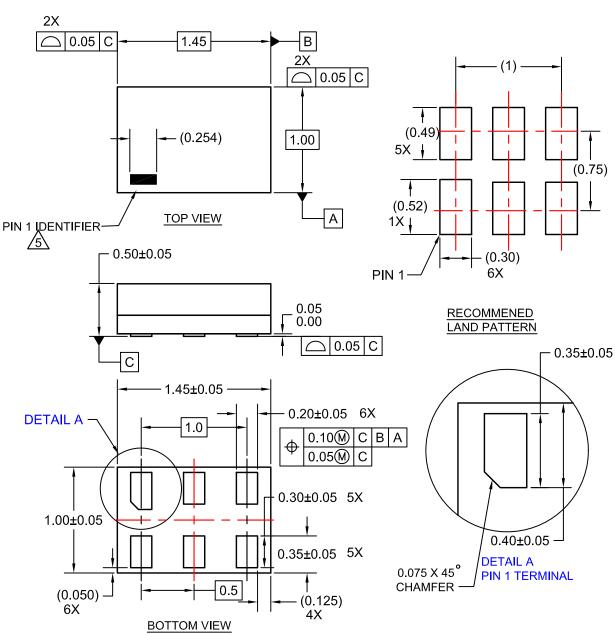
Direction of Feed



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PACKAGE DIMENSIONS

SIP6 1.45X1.0 CASE 127EB ISSUE O

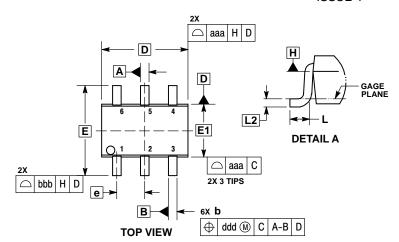


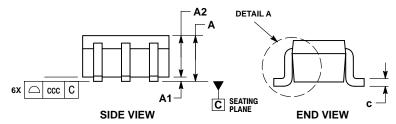
- NOTES:
- 1, CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-2009
- 4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY
 - OTHER LINE IN THE MARK CODE LAYOUT.

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363

CASE 419B-02 ISSUE Y





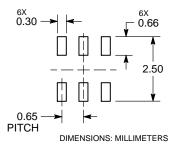
- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
 4. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
 5. DATUMS A AND B ARE DETERMINED AT DATUM H.
 6. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.05 AND 0.15 FROM THE TIP.
 7. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION

- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION.
 ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN
 EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α			1.10			0.043	
A1	0.00		0.10	0.000		0.004	
A2	0.70	0.90	1.00	0.027	0.035	0.039	
b	0.15	0.20	0.25	0.006	0.008	0.010	
С	0.08	0.15	0.22	0.003	0.006	0.009	
D	1.80	2.00	2.20	0.070	0.078	0.086	
E	2.00	2.10	2.20	0.078	0.082	0.086	
E1	1.15	1.25	1.35	0.045	0.049	0.053	
е		0.65 BS	0	0.026 BSC			
L	0.26	0.36	0.46	0.010	0.014	0.018	
L2		0.15 BS	C	(0.006 BS	SC	
aaa	0.15				0.006		
bbb	0.30			0.012			
ccc	0.10			0.004			
ddd		0.10			0.004		

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NTE4028B NTE4514B NTE4515B NTE4543B NTE4547B NTE74LS249 NLV74HC4851AMNTWG MC74LVX257DG
M74HCT4851ADWR2G AP4373AW5-7-01 NL7SZ19DBVT1G MC74LVX257DTR2G 74VHC4066AFT(BJ) 74VHCT138AFT(BJ)
74HC158D.652 74HC4052D(BJ) 74VHC138MTC COMX-CAR-P1 JM38510/65852BEA 74VHC138MTCX 74HC138D(BJ)
NL7SZ19DFT2G 74AHCT138T16-13 74LCX138FT(AJ) 74LCX157FT(AJ) NL7SZ18MUR2G PCA9540BD,118 QS3VH16233PAG8
SNJ54HC251J SN54LS139AJ SN74CBTLV3257PWG4 SN74ALS156DR SN74AHCT139PWR 74HC251D.652 74HC257D.652